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Jameco Part Number 819438

19-1353; Rev 1; 6/03 EVALUATION KIT MANUAL FOLLOWS DATA SHEET

Dual-Output (Positive and Negative), DC-DC Converter for CCD and LCD

General Description

The MAX685 DC-DC converter provides low-noise dual outputs for powering CCD imaging devices and LCDs. This device uses a single inductor to provide independently regulated positive and negative outputs. Integrated power switches are included in a small 24-Pin 4mm x 4mm Thin QFN package to save space and reduce cost. A 16-pin QSOP package is also available.

Each output delivers up to 10mA from a +2.7V to +5.5V input voltage range. Output voltages are set independently up to 24V and down to -9V. With a few additional low-cost components, the output voltages can be set at up to 45V and down to -16V. Output ripple magnitude is 30mVp-p. The MAX685 uses a fixed-frequency, pulsewidth-modulated (PWM) control scheme at 220kHz or 400kHz to permit output noise filtering and to reduce the size of external components. The frequency can also be synchronized to an external clock signal between 200kHz and 480kHz.

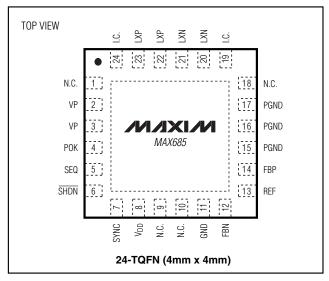
The MAX685 has a power-OK indicator output (POK) that signals when both outputs are within regulation. A logic-controlled shutdown completely turns off both outputs and reduces supply current to 0.1µA. The user can also set which output turns on first.

The preassembled MAX685 evaluation kit is available to reduce design time.

Applications

Camcorders	LCDs
Digital Cameras	CCD Imaging Devices
Notebooks	

Pin Configuration



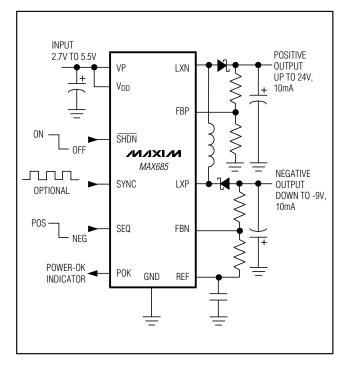
Features

- Dual Output Using a Single Inductor
- ♦ Low-Noise Output, 30mVp-p Ripple
- ♦ Output Voltages up to 24V and down to -9V (up to 45V and down to -16V with added components)
- ♦ Internal Switches in a Small 24-Pin 4mm x 4mm Thin QFN Package
- ♦ 220kHz/400kHz Fixed-Frequency PWM Operation
- ♦ Frequency Can Be Synchronized to External Clock
- ♦ Power-OK Indicator
- ♦ Selectable Power-On Sequencing
- ♦ 0.1µA Logic-Controlled Shutdown

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX685EEE	-40°C to +85°C	16 QSOP
MAX685ETG	-40°C to +85°C	24 TQFN

Typical Operating Circuit



MIXIM

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

V _{DD} , VP to GND	0.3V to +6V
PGND to GND	0.3V to +0.3V
V _{DD} to VP	0.3V to +0.3V
LXN, POK to GND	0.3V to +30V
LXP to V _{DD}	
REF, SEQ, SHDN to GND	$0.3V$ to $(V_{DD} + 0.3V)$
FBP, FBN, SYNC to GND	0.3V to +6V

Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
16-Pin QSOP (derate 8.3mW/°C above +70°C)	667mW
24-Pin TQFN (derate 20.8mW/°C above +70°C)	1667mW
Operating Temperature Range40	°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range65°	
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = VP = 5V, T_A = 0^{\circ}C \text{ to } +85^{\circ}C \text{ unless otherwise noted.}$ Typical values are at $T_A = +25^{\circ}C.)$

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Voltage Range	$V_{DD} = VP$	2.7		5.5	V
Positive Output Voltage Range		VP		24	V
Negative Output Voltage Range	V _{DD} = 5.5V (Note 1)	-9		-1.27	V
Output Current	$V_{DD} = 4.5V, V_{OUT+} \ge 14.25V, V_{OUT-} \le -7.125V,$ Figure 3	10			mA
LX Current Limit	T _A = +25°C		440		mA
LXP, LXN On-Resistance	V _{DD} = 4.5V		0.6	2	Ω
Quiescent Current	SYNC = V _{DD}		0.8		mA
Idle Quiescent Current	V _{FBP} = 1.35V, V _{FBN} = -0.1V		300	500	μA
Line Regulation	V _{DD} = 4.5V to 5.5V		0.2		%/V
Load Regulation	I _{OUT} = 0 to 10mA, C1 = 10μF		0.13		%/mA
Output Voltage Ripple	$C3 = C4 = 10\mu F$, $I_{LOAD} = 5mA$		30		mVp-p
SHUTDOWN (SHDN)					
Shutdown Supply Current	SYNC = SEQ = SHDN = GND		0.1	10	μΑ
UNDERVOLTAGE LOCKOUT		1.			ı
UVLO Threshold	V _{DD} = rising	2.35	2.5	2.65	V
UVLO Hysteresis			50		mV
REFERENCE VOLTAGE		<u>.</u>			
VREF Output Voltage	No load	1.23	1.250	1.27	V
V _{REF} Load Regulation	0 < I _{REF} < 50μA		-2		mV
FB INPUTS		·			
FBP Threshold Voltage	No load	1.21	1.24	1.27	V
FBN Threshold Voltage	No load	-16	10	36	mV
FBP, FBN Input Leakage Current			±0.01	±0.1	μΑ
LOGIC INPUTS (SEQ, SHDN, SYNO					
Logic-Low Input	2.7V < V _{DD} < 5.5V		0	.3 x V _{DD}	V
Logic-High Input	2.7V < V _{DD} < 5.5V	0.7 x V _{DD}			V
Input Bias Current			0.1	1	μΑ

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = VP = 5V, T_A = 0$ °C to +85°C unless otherwise noted. Typical values are at $T_A = +25$ °C.)

PARAMETER	CONDITIONS	М	IN	TYP	MAX	UNITS
SYNC INPUT						
Sync Frequency Range (external)		20	OC		480	kHz
Oscillator Fraguency (internal)	SYNC = GND	17	75	220	265	kHz
Oscillator Frequency (internal)	$SYNC = V_{DD}$	32	20	400	480	K ∏∠
POK COMPARATORS						
FBP POK Threshold	FBP rising	1.0)90	1.122	1.150	V
FBN POK Threshold	FBN falling	5	64	79	108	mV
POK Output Low Voltage	I _{POK} = 2mA				0.4	V
POK Output Off Current	V _{POK} = 10V				1	μΑ

ELECTRICAL CHARACTERISTICS

 $(V_{DD}, VP = 5V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C \text{ unless otherwise noted.})$ (Note 2)

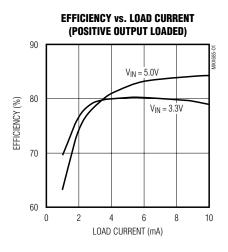
PARAMETER	CONDITIONS	MIN	MAX	UNITS
Input Voltage Range	V _{DD} = VP	2.7	5.5	V
Positive Output Voltage Range		VP	24	V
Negative Output Voltage Range	V _{DD} = 5.5V (Note 1)	-9	-1.27	V
Maximum Output Current	$V_{IN} = 4.5V$, $V_{OUT+} \ge 14.25V$, $V_{OUT-} \le -7.125V$, Figure 3	10		mA
Idle Quiescent Current	SYNC = GND		500	μΑ
SHUTDOWN				
Shutdown Supply Current	SYNC = SEQ = SHDN = GND		10	μΑ
UNDERVOLTAGE LOCKOUT				
UVLO Threshold	V _{DD} = rising	2.35	2.65	V
FB INPUTS AND REFERENCE VOI	TAGE	<u>.</u>		
FBP Threshold Voltage	No load	1.205	1.275	V
FBN Threshold Voltage	No load	-20	40	mV
VREF Output Voltage	No load	1.225	1.275	V
LOGIC INPUTS (SEQ, SHDN, SYNC	;)		<u>.</u>	
Logic-Low Input	2.7V < V _{DD} ≤ 5.5V		0.3 x V _{DD}	V
Logic-High Input	2.7V < V _{DD} ≤ 5.5V	0.7 x V _{DD}		V
POK COMPARATORS		•		
FBP POK Threshold	FBP rising	1.090	1.150	V
FBN POK Threshold	FBN falling	54	108	mV

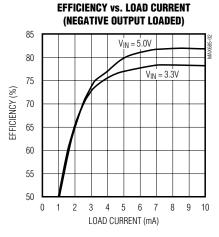
Note 1: Negative output voltage can be larger magnitude for lower values of V_{DD}. The voltage between V_{DD} and V_{OUT}- must not exceed 14.5V.

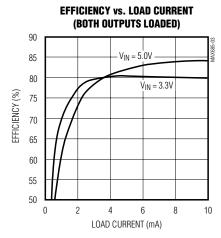
Note 2: Specifications to -40°C are guaranteed by design, not production tested.

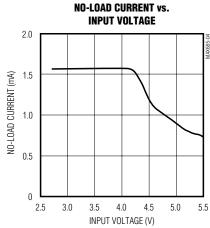
Typical Operating Characteristics

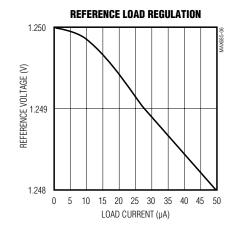
(Circuit of Figure 3, V_{OUT+} = 15V, V_{OUT-} = -7.5V, T_A = +25°C, unless otherwise noted.)

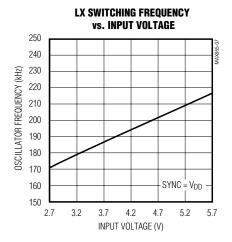


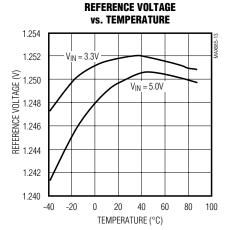






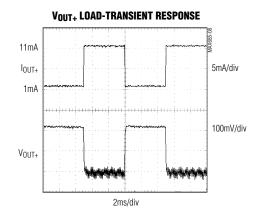


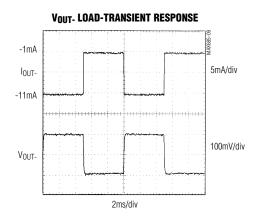




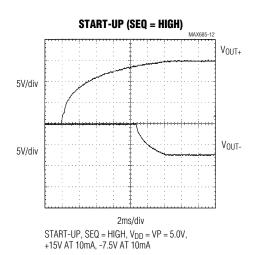
Typical Operating Characteristics (continued)

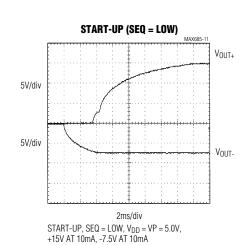
(Circuit of Figure 3, V_{OUT+} = 15V, V_{OUT-} = -7.5V, T_A = +25°C, unless otherwise noted.)





100mV/div 100mV/div 2V/div 1ms/div INPUT 4V TO 5V, +15V AT 10mA, -7.5V AT 10mA





Pin Description

PIN 16-QSOP	PIN 24-TQFN	NAME	FUNCTION
1	22, 23	LXP	P-Channel Switching Inductor Node. LXP turns off when the part enters shutdown.
2, 15	19, 24	I.C.	Internally Connected. Do not externally connect.
3	2, 3	VP	Power Input. Connect to V _{DD} .
4	4	POK	Open-Drain Power-OK Output. POK is high when both outputs are in regulation. Connect POK to V_{DD} with a $100 k\Omega$ pull-up resistor to V_{DD} .
5	5	SEQ	Power-Up Sequence Select Input. Connect SEQ to GND to power the negative output voltage first. Connect SEQ to V _{DD} to power the positive output first.
6	6	SHDN	Shutdown Input. Both outputs go to 0V in shutdown. Connect to VDD for automatic startup.
7	7	SYNC	Sync Input. This pin synchronizes the oscillator to an external clock frequency between 200kHz and 480kHz. Connect SYNC to GND (220kHz) or V _{DD} (400kHz) for internal oscillator frequency.
8	8	V_{DD}	Supply Input. Bypass V _{DD} with a 1.0µF or greater ceramic capacitor to GND.
9	11	GND	Ground
10	12	FBN	Feedback Input for the Negative Output Voltage. Connect a resistor-divider between the negative output and REF with the center to FBN to set the negative output voltage.
11	13	REF	1.25V Reference Voltage Output. Bypass with 0.22µF to GND.
12	14	FBP	Feedback for the Positive Output Voltage. Connect a resistor-divider between the positive output and GND with the center to FBP to set the positive output voltage.
13, 14	15, 16, 17	PGND	Power Ground. Connect PGND to GND.
16	20, 21	LXN	N-Channel Switching Inductor Node. LXN pulls to GND through the internal transistor when the part is shut down.
_	1, 9, 10, 18	N.C.	This pin in not internally connected.

Detailed Description

The MAX685 DC-DC converter accepts an input voltage between +2.7V and +5.5V and generates both a positive and negative voltage, using a single inductor (Figure 1). It alternates between acting as a step-up converter and as an inverting converter on a cycle-by-cycle basis. Both output voltages are independently regulated.

Each output is separately controlled by a pulse-width-modulated (PWM) current mode regulator. This allows the part to operate at a fixed frequency for use in noise-sensitive applications. An internal oscillator runs at 220kHz or 400kHz, or can be synchronized to an external signal. Since switching alternates between the two regulators, each operates at half the oscillator frequency (110kHz, 200kHz, or half the sync frequency). The oscillator can be synchronized to a 200kHz to 480kHz clock.

On the first cycle of operation, the part operates as a step-up converter. LXP connects to V_{DD}, LXN pulls to ground, and the inductor current rises. Once the inductor current rises to a level set by the positive-side error amplifier, LXN releases and the inductor current flows through D2 to the positive output. When the inductor current drops to zero (which happens each cycle under normal, discontinuous operation), LXN returns to the input voltage.

On the second cycle, LXN is held at ground. LXP is pulled up to the input voltage until the current reaches the limit set by the negative error amplifier. Then LXP is released and the inductor current flows through D1 to the negative output. Once the inductor current reaches zero, the voltage at LXP returns to ground. The waveforms at LXN and LXP are shown in Figure 2 for a typical pair of cycles.

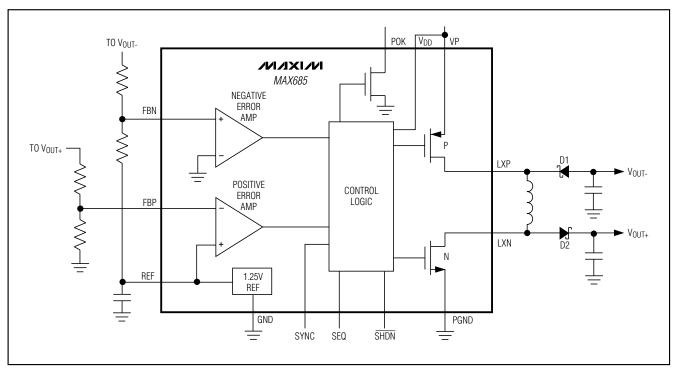


Figure 1. Functional Diagram

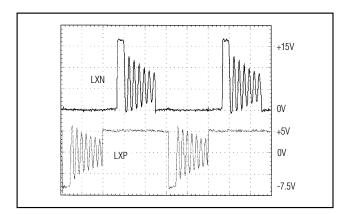


Figure 2. LXN and LXP Waveforms (see also Figure 5)

The current into the LXN pin is sensed to measure the inductor current. The MAX685 controls the inductor current to regulate both the positive and negative output voltages.

SEQ and Power OK (POK)

The SEQ pin controls the power-up sequence. If SEQ is low, the positive output is disabled until the negative output is within 90% of its regulation point. If SEQ is high, the negative output is disabled until the positive

output is within 90% of its regulation point. The power-OK output (POK) indicates that both output voltages are in regulation. When both outputs are within 90% of their regulation points, POK becomes high impedance. Should one or both of the output voltages fall below 90% of their regulation points, POK pulls to ground. POK can sink up to 2mA. To reduce current consumption, POK is high impedance while the part is in shutdown. When coming out of shutdown, POK remains high impedance for 50ns (typ) before going low. Connect POK to VDD through a $100 k\Omega$ resistor.

Synchronization/Internal Frequency Selection

The MAX685 operates at a fixed switching frequency. Set the operating frequency using the SYNC pin. If SYNC is grounded, the part operates at the internally set 220kHz frequency. When SYNC is connected to VDD, the part operates at 400kHz. The MAX685 can also be synchronized to signals between 200kHz and 480kHz. Note that each output switches at half the oscillator or synchronized frequency. Since the actual switching frequency is one-half the applied clock signal, drive SYNC at twice the desired switching frequency.

Applications Information

Figure 3 shows the standard application circuit for the MAX685. The values shown in Table 1 will work well for output currents up to 10mA. However, this circuit can be optimized to a particular application by using different capacitors and a different inductor.

Higher Output Voltages

If the application requires output voltages greater than -7.5V or +24V, use the circuit of Figure 4. This circuit uses a charge pump to increase the output voltage without increasing the voltage stress on the LX_ pin. The maximum output voltages of the circuit in Figure 4 are -15V and +48V.

The voltage rating on D2, D5, and D6 must be 30V or greater. For a larger negative output voltage without a larger positive output (or vice versa), use one-half of the Figure 4 circuit with one-half of the Figure 3 circuit.

Inductor Selection

A 22µH inductor is suitable for most applications. Larger inductances will reduce inductor ripple current and output voltage ripple, but they also typically require larger physical size if increased resistance and losses are not also allowed.

 V_{IN} ____+ C1 \leq R5 ⊃10μF 100k C2 0.22µF REF VP V_{DD} POK POK \leq R4 MIXIM > 124k MAX685 SHDN **SHDN** SYNC SYNC FBN FRP $\begin{array}{c}
R2 \\
90.9k
\end{array}$ C5 GND PGND LXN ≤R3 750k 47pF R1 > -7.5V +15V V_{OUT}. V_{OUT+} L1 D1 D2 22µH C3 + C4 MBR0520 MBR0520 2.2µF - 2.2μF

Figure 3. Standard Application Circuit

Small inductors are typically preferred because of compact design and low cost. Murata LHQ and TDK NLC types are examples of small surface-mount inductors that work for most applications. Because these small-size inductors use thinner wire, they exhibit higher resistance and have greater losses than larger ones. If the application demands higher efficiency, use larger, lower resistance coils such as the Sumida CD43 or CD54, Coilcraft DT1608 or DO1608, or Coiltronics UP1V series.

Filter Capacitor Selection

The output ripple voltage is a function of the peak inductor current, frequency, and type and value of the output capacitors. Capacitors with low equivalent-series resistance (ESR) and large capacitance reduce output ripple. Typically, tantalum or ceramic capacitors are optimal. Tantalum capacitors have higher ESR and higher capacitance than ceramic capacitors. Therefore the ESR of tantalum capacitors determines the output ripple, because at the frequencies used the ESR dominates the impedance of the capacitor. If ceramic capacitors are used, the capacitance determines the output ripple.

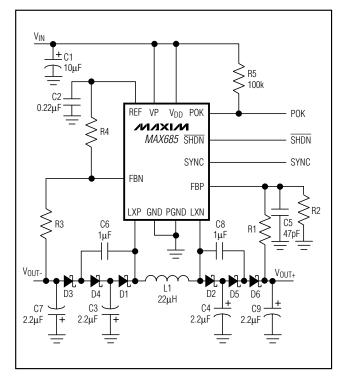


Figure 4. Circuit for Output Voltages < -9V and > +24V

Table 1. Component Values for the Typical Operating Circuit

REF	DESCRIPTION	MANUFACTURER PART NUMBER
C1	10µF, 10V tantalum cap	Sprague 595D106X0010A2T or AVX TAJA106K010R
C2	0.22µF ceramic capacitor	Any manufacturer
C3, C4	2.2µF ceramic capacitor	Any manufacturer
C5	47pF ceramic cap	Any manufacturer
D1, D2	0.1A, 20V Schottky rectifier	Motorola MBR0520LT1 (0.5A) or Central Semiconductor CMPSH-3
L1	22µH, 0.4A inductor	Murata LHQ4N220J04 or TDK NLC32522T-220K

Setting the Output Voltage

The resistor-divider formed by R4 and R3 sets the negative output voltage; the resistor-divider formed by R1 and R2 sets the positive output voltage. Let R4 be a value near $100k\Omega$ to set a resistor-divider current of approximately $10\mu\text{A}$. Determine the value of R3 by the following:

$$R3 = R4 \frac{|V_{OUT}|}{1.24V}$$

Let R2 be a value near $100k\Omega$ to set a resistor-divider current of approximately $10\mu A$. Determine the value of R1 with the following formula:

$$R1 = R2 \times (V_{OUT} + -1.24V) / 1.24$$

Damping LX

LXN and LXP may ring at the conclusion of each switching cycle when the inductor current falls to zero. Typically the ringing waveform appears only on LX_ and has no effect on output ripple and noise. If LX_ ringing is still objectionable, it may be damped by connecting a series RC in parallel with L1. Typically $1k\Omega$ in series with 100pF provides good damping with only 3% efficiency degradation. See Figure 5.

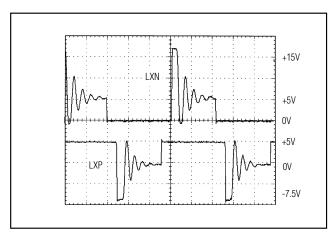


Figure 5. LXN and LXP Waveforms with a Series-Connected $1k\Omega$ Resistor and 100pF Capacitor Connected in Parallel with L1 to Damp Ringing

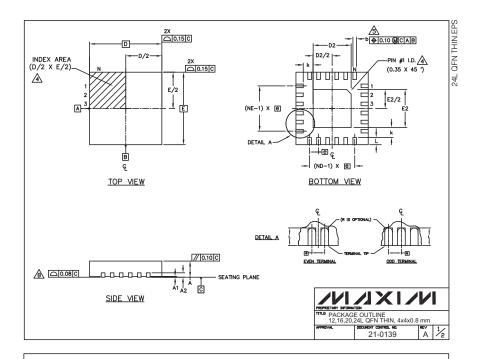
Chip Information

TRANSISTOR COUNT: 902

SUBSTRATE CONNECTED TO GND

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.



	COMMON DIMENSIONS											
PKG	1	2L 4×4	_	1	16L 4×4		2	20L 4×4 24L 4×4		4		
REF.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05
A2		0.20 REF		0.20 REF		0.20 REF		0.20 REF				
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
E	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
e		0.80 BSC.		0.65 BSC.		0.50 BSC.			0.50 BSC			
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50
N		12			16			20			24	
ND		3		4		5			6			
NE		3		4		5		6				
Jedec Vor		WGGB			WGGC			WGGD-	1 WGGD-2			2

EXPOSED PAD VARIATIONS							
PKG.		DS		E2			
CODES	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	
T1244-2	1.95	2.10	2.25	1.95	2.10	2.25	
T1644-2	1.95	2.10	2.25	1.95	2.10	2.25	
T2044-1	1.95	2.10	2.25	1.95	2.10	2.25	
T2444-1	2.45	2.60	2.63	2.45	2.60	2.63	

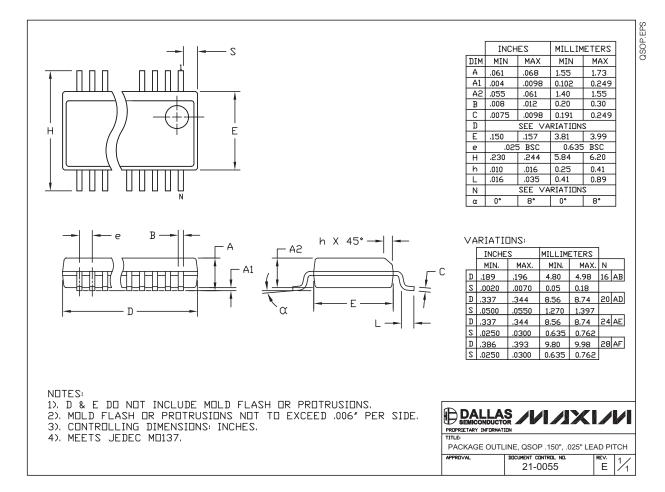
- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
 ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
 N IS THE TOTAL NUMBER OF TERMINALS.

- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO
 JESO 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN
 THE ZONE NIDICATED, HE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.
- NO AND ME REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
 DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- (A) COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220.

/VI/XXI/VI								
	PACKAGE OUTLINE 12,16,20,24L QFN THIN, 4x4x0.8 mm							
APPROVAL	21-0139	A	2/2					

Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



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